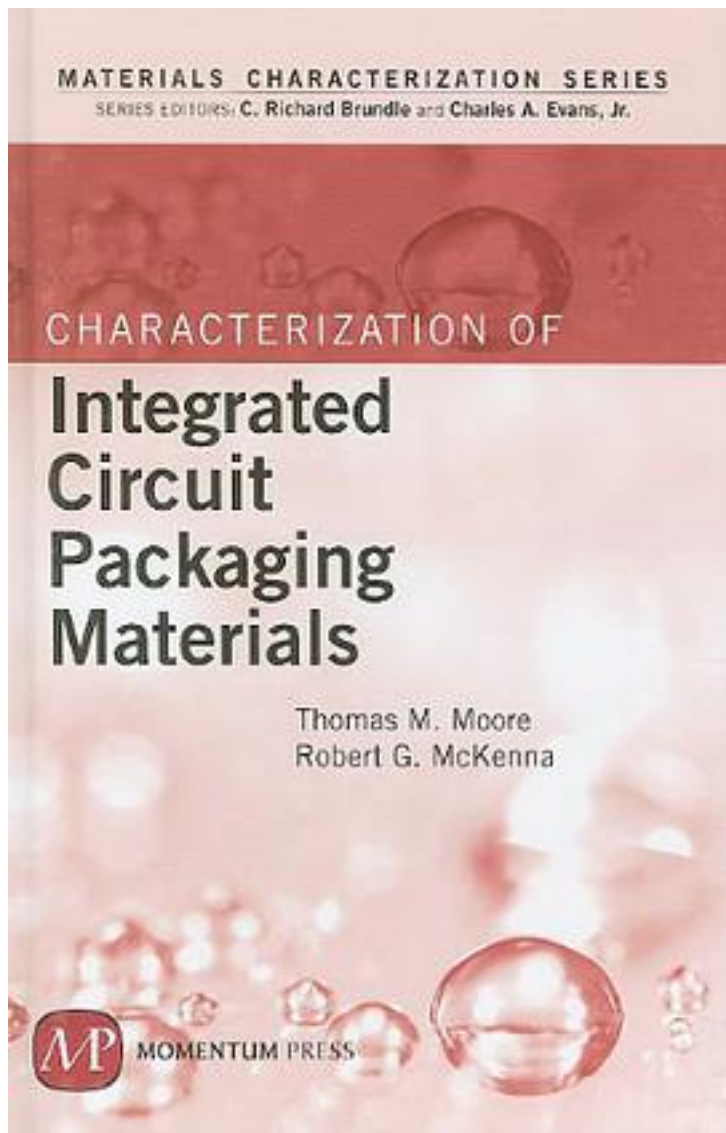


Characterization of Integrated Circuit Packaging Materials (Materials Characterization Series)



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出版者:Momentum Press

出版时间:2010-03

装帧:Hardcover

isbn:9781606501870

作者介绍:

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